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Docket No.:

ocket No.: 005917 USA/FET/FET

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Young Joseph PAIK

Serial No. 09/998,372

Group Art Unit: 3723

Filed: November 30, 2001

Examiner: Robert A. Rose

For:

CONTROL OF CHEMICAL MECHANICAL POLISHING PAD CONDITIONER

DIRECTIONAL VELOCITY TO IMPROVE PAD LIFE

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

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to present to the Office the relevant facts and law regarding the appropriate status of such

document.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a

patentability investigation and/or a corresponding foreign or PCT application relating to the

above-referenced application. The remaining references are from potentially related patent

applications, and possibly other sources.

Please charge the fee of \$180.00 under 37 CFR 1.17(p) to Deposit Account No. 08-0219.

The Commissioner is hereby authorized to charge any additional fees that may be required for

this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

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Date: 8/4/04

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ATTY. DOCKET NO. SERIAL NO. INFORMATION DISCLOSURE 09/998,372 005917 USA/FET/FET CITATION IN AN **APPLICATION** (PTO-1449) **APPLICANT** Young Joseph PAIK FILING DATE GROUP 3723 November 30, 2001

U.S. PATENT DOCUMENTS EXAMINER'S FILING **INITIALS** PATENT NO. DATE NAME **CLASS SUBCLASS** DATE 07/09/98 6,059,636 05/09/00 Inaba et al. OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) April 29, 2004. Written Opinion for PCT/US02/19061. **EXAMINER DATE CONSIDERED**

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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INFORMATION DISCLOSURE
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(PTO-1449)

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APPLICANT
Young Joseph PAIK

FILING DATE GROUP November 30, 2001 3723

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